

**OMNIMATE Data - Jack RJ45
RJ45C6 R1V 3.2N4N TY**

Weidmüller Interface GmbH & Co. KG
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L'assortimento prodotti include i seguenti modelli:

- 90° orizzontale e 180° verticale
- con gancio verso l'alto / gancio verso il basso
- Processi di saldatura THT, THR o SMD
- Ampia gamma di forme diverse, anche con LED integrati e linguette per contatto schermato
- Categoria di prestazione da Cat. 3 a Cat. 6
- Versione con imballaggio in vassoio (TY) o su rotolo (Tape-on-Reel, RL)

Caratteristiche e vantaggi:

- Intervallo di temperatura ampliato da -40 °C a +85 °C per la massima capacità di prestazioni
- Lato dorato rinforzato (30µ") per una migliore protezione anticorrosione
- Il supporto di almeno 3 mm assicura una perfetta saldatura

Dati generali per l'ordinazione

Tipo	RJ45C6 R1V 3.2N4N TY
Nr.Cat.	2634590000
Versione	Connettore per circuito stampato, Jack RJ45, Collegamento a saldare THT/THR, 180°, Numero di poli: 8
GTIN (EAN)	4050118651270
CPZ	160 Pezzo

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Dati tecnici**Dimensioni e peso**

Peso netto	7,475 g
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Conformità ambientale del prodotto

REACH SVHC	Lead 7439-92-1
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Specifiche di sistema

Angolo di uscita	180°	Cicli di inserimento	750
Famiglia prodotti	OMNIMATE Data - Jack RJ45	Grado di protezione	IP20
Montaggio su circuito stampato	Collegamento a saldare THT/THR	Numero di poli	8
Superficie di schermatura	nichelato		

Imballaggio

Lunghezza VPE	0,315 m	Larghezza VPE	0,195 m
Altezza VPE	0,065 m		

Classificazioni

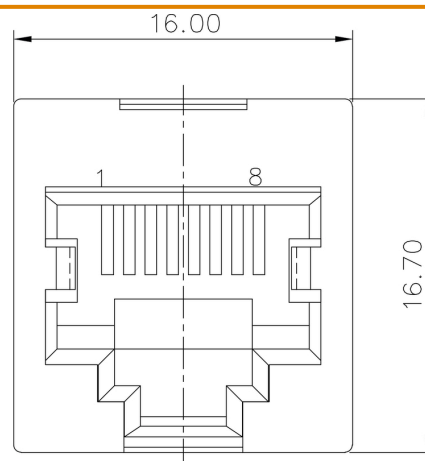
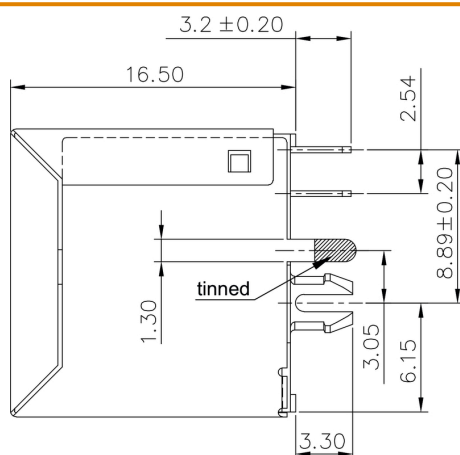
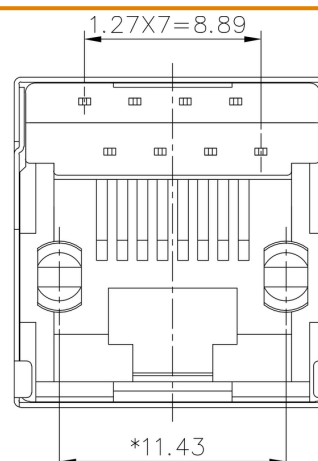
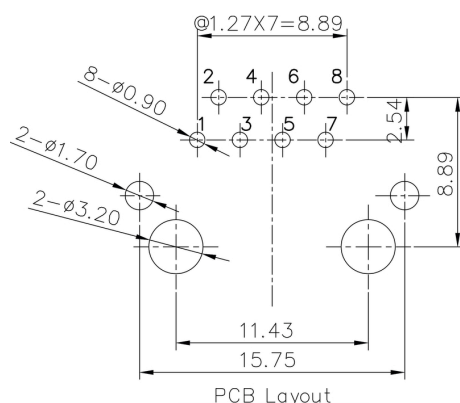
ETIM 6.0	EC002637	eClass 6.2	27-26-07-04
eClass 9.0	27-44-04-02	eClass 9.1	27-44-04-02

Approvazioni

ROHS	Conforme
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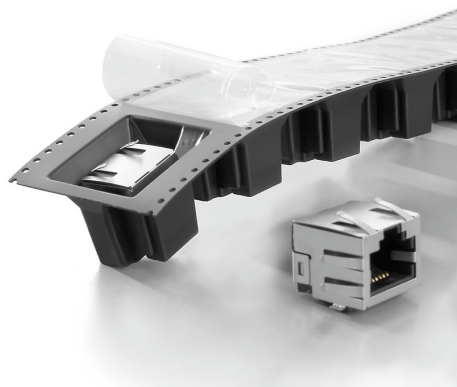
Disegni
Disegno quotato

Disegno quotato

Disegno quotato

Disegno del circuito stampato


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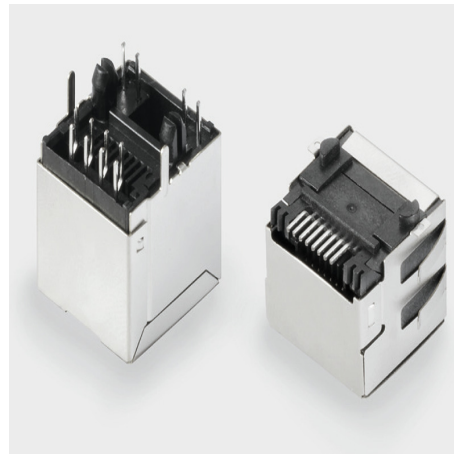
Vantaggi del prodotto



Process-optimised packaging
Tape-on-reel or tray

Vantaggi del prodotto

Vantaggi del prodotto



Trouble-free assembly
Short, chamfered solder pins



Suitable for all soldering processes
SMT, THT or THR

Data di creazione 12 giugno 2019 17.47.34 CEST

Versione catalogo 07.06.2019 / Con riserva di modifiche tecniche

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Disegni

Legenda

RJ45	G	R	I	U	3	E	4	G/Y/GY	T	J45G1 R1 U3 E4 G/Y/GY T
								Packaging	TY RL	Tray in box (manual assembly) Tape on Reel (automated assembly)
								LED	Y/G G/Y GY/GY O/O R/O ... N	Yellow/Green Green/Yellow (standard) Yellow/Green-Yellow Orange-Green Red/Orange ... (further combinations possible) without LED
								Contact surface thickness	4	1 = 3µ", 2 = 6µ", 3 = 15µ", 4 = 30µ", 5 = 50µ"
								EMI tabs (ground fingers)	E N	E = with EMI tabs N = without EMI tabs
								Solder Pin length	3.2 1.6 D	3.2 mm 1.6 mm SMD
								Direction, latch style	U D V Y	Horizontal (90°, side entry), latch up Horizontal (90°, side entry), latch down Vertical (180°, top entry) Diagonal (45°), latch up
								Number of Ports	1 12; 14; ... 21; 41; ...	1 Port multi ports side by side, Multiport multi ports about each other, Multilevel
								Assembly on PCB	R S T	Through Hole Reflow - THR Soldering process: Wave or Reflow soldering Surface Mount Technology - SMT Soldering process: Reflow soldering Through Hole Technology - THT Soldering process: Wave
								Performance Category	C5 C6 CSA C5e M G1 G10 U NP NP+	Category 5 Category 6 Category 6A Category 5e 10/100 Mbit 10/100/1000 Mbit 10 Gbit Unshielded 10/100 Mbit with POE 10/100 Mbit with POE+

Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.